

The Application of Simulation Kit Using USB3.0 IBIS-AMI Model

Motoaki Matsumura
FUJITSU SEMICONDUCTOR LIMITED

Asian IBIS Summit
Yokohama, JAPAN
November 16, 2012

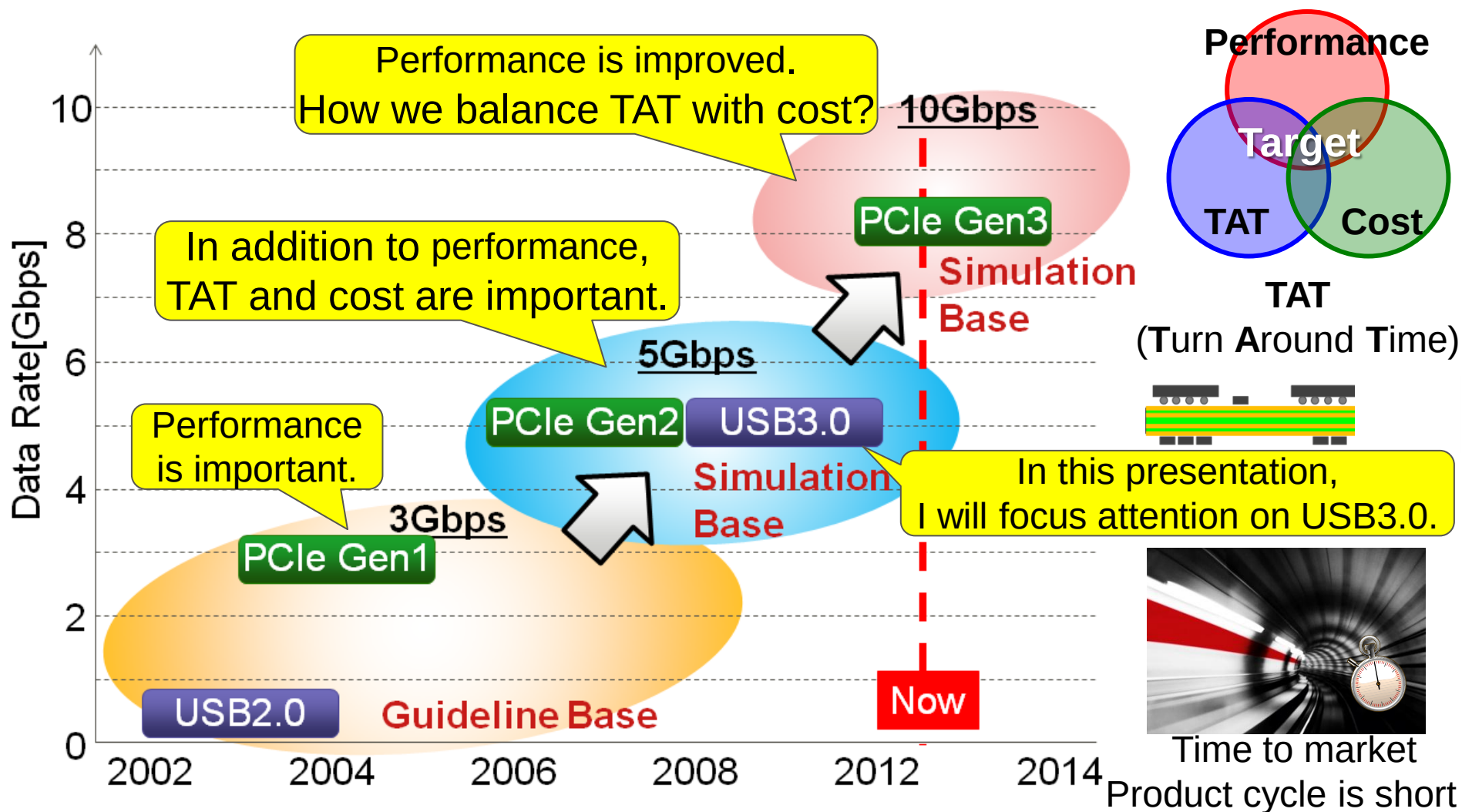
- USB3.0 Compliance Simulation using IBIS-AMI Model
- Summary
- Expectation of IBIS-AMI

- USB3.0 Compliance Simulation using IBIS-AMI Model
- Summary
- Expectation of IBIS-AMI

Chip-PKG-PCB Co-Design of SerDes I/F

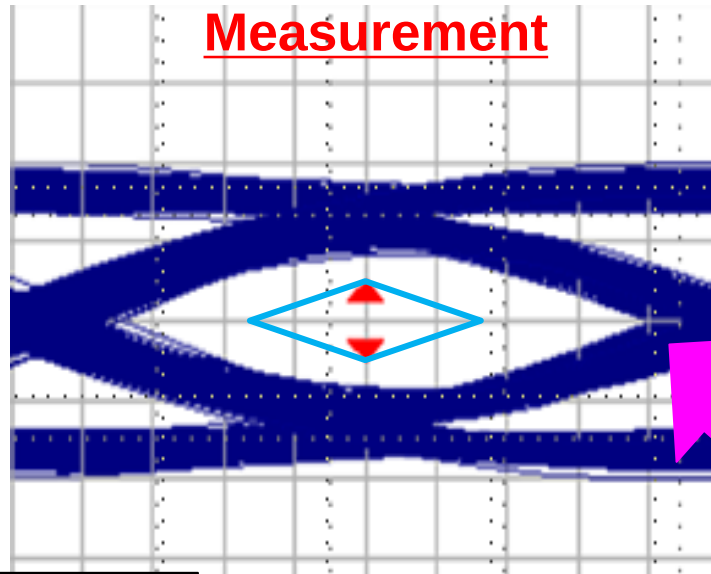
■ **5Gbps SerDes I/F become prevalent, for example USB3.0.**

■ We want to bring a new product to market more quickly.



[Conclusion] : Only 0.5h for USB3.0 Analysis **FUJITSU**

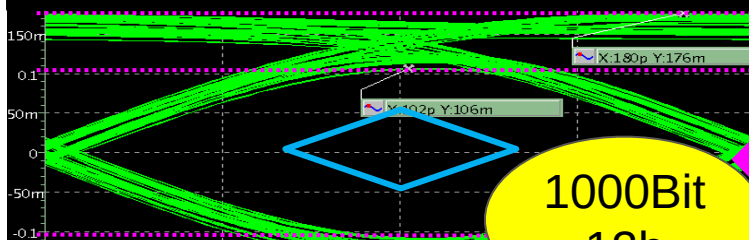
■ Measurement vs Simulation



Simulation is possible many times at the initial designing stage.

match

Spice Net Transient Analysis



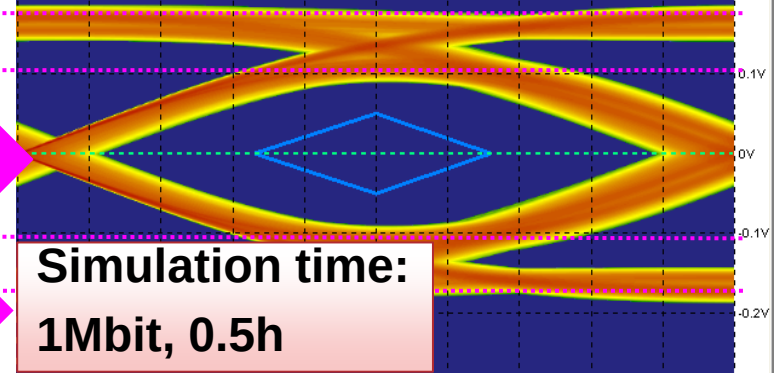
Simulation time:
1Mbit(Conversion), 120,000h

1000Bit
12h

match

1/240,000

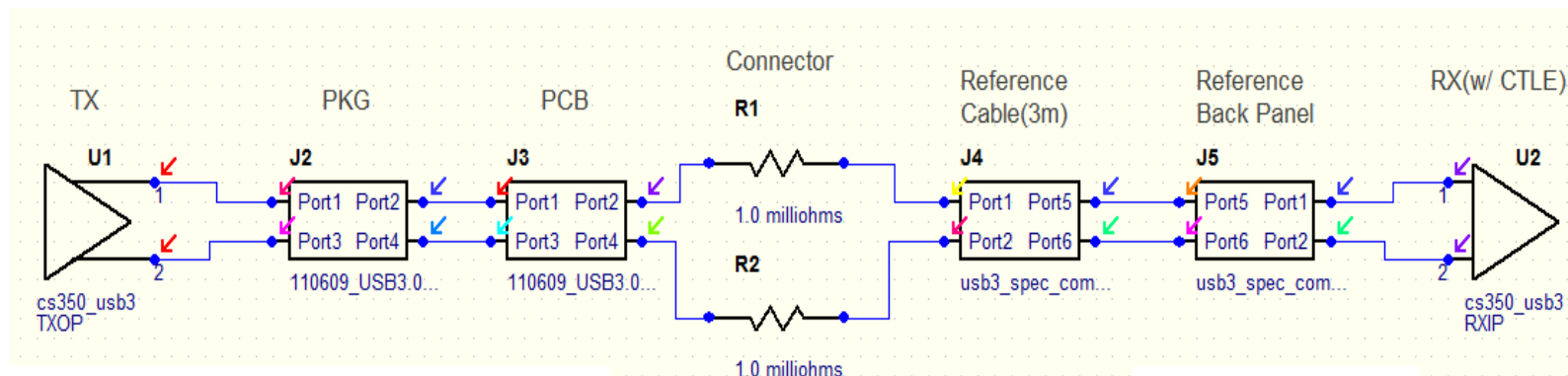
IBIS-AMI Channel Analysis



Simulation time:
1Mbit, 0.5h

IBIS-AMI enables a high accuracy and short TAT analysis.

■ USB3.0 Compliance Test Simulation Kit on EDA Tool



Semiconductor Vendor

- (1) Simulation Kit that reflected reference design.
- (4) The support of customer's difference analysis is easy.

Customer

- (2) Customer can judge the quality of own design quantitatively.
- (3) Customer can execute differential analysis in a short TAT. (IBIS-AMI + EDA tool)

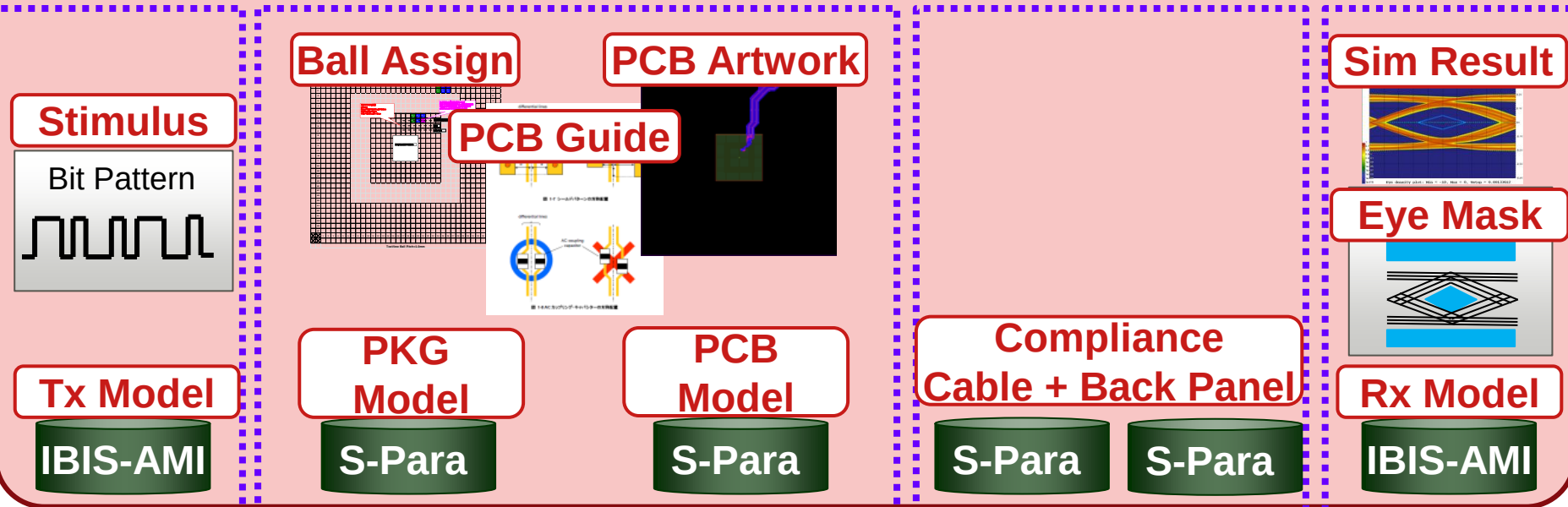
EDA Vender

- (5) EDA tool support.

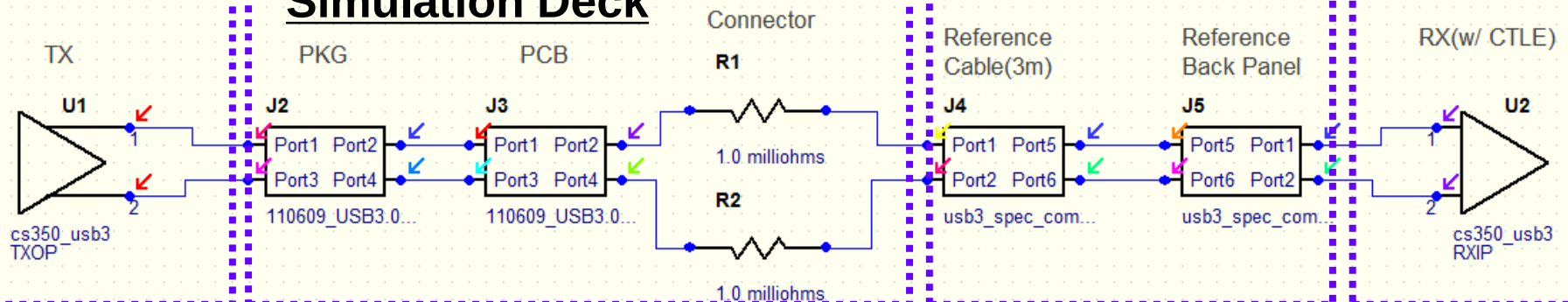
Simulation Kit can prevent the troubles, for example mismatch between IBIS-AMI and EDA tool, the usage of EDA tool.

Simulation Kit

Reference Design



Simulation Deck



Compliance Test Pattern (Stimulus)

■ USB3.0 Tx Compliance Test Pattern & Transmitter Eye

“Universal Serial Bus 3.0 Specification Revision 1.0”

6.7.3 Transmitter Eye

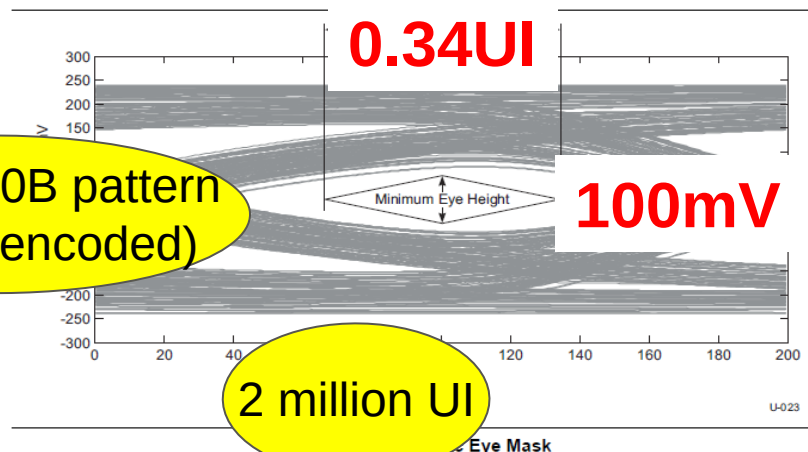
The eye mask is measured using the compliance data patterns (CP0 for DJ and CP1 for RJ) as described in Section 6.4.4. Eye height is measured for 10⁶ consecutive UI. Jitter is extrapolated from 10⁶ UI to 10⁻¹² BER.

Table 6-7. Compliance Pattern Sequences

Compliance Pattern	Value	Description
CP0	D0.0 scrambled	A pseudo-random pattern in logical idle (refer to Chapter 7) bit sequences
CP1	D10.2	Nyquist frequency

CP1
Repeat Pattern
of 0, 1

CP0 : 8B/10B pattern
(PRBS is encoded)



Eye Height, Jitter(10⁻¹²BER) Measurement

CP0x10⁶ UI + CP1x10⁶ UI

Simulation time is too long in Spice Net
Transient Analysis

about 5000 days!

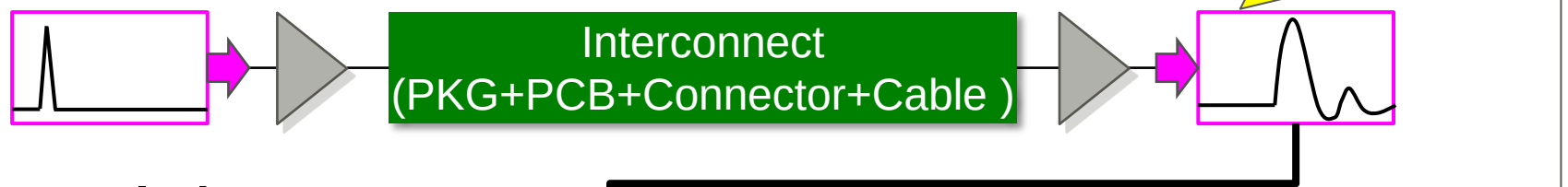
Channel Analysis using IBIS-AMI

about 0.5 hours!

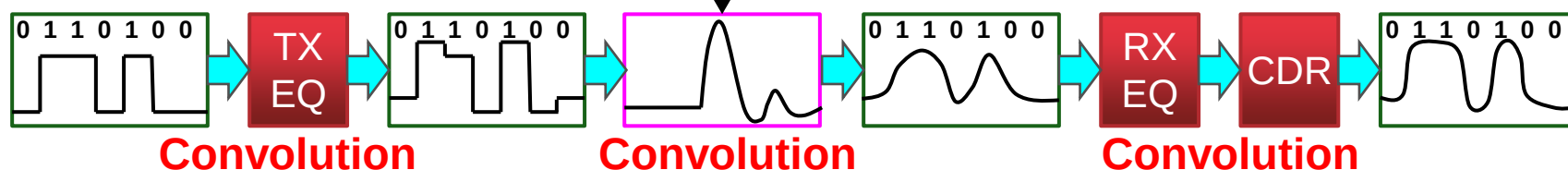
Speed up Simulation Time

■ Channel Analysis

1. Analog Channel Impulse Response Process



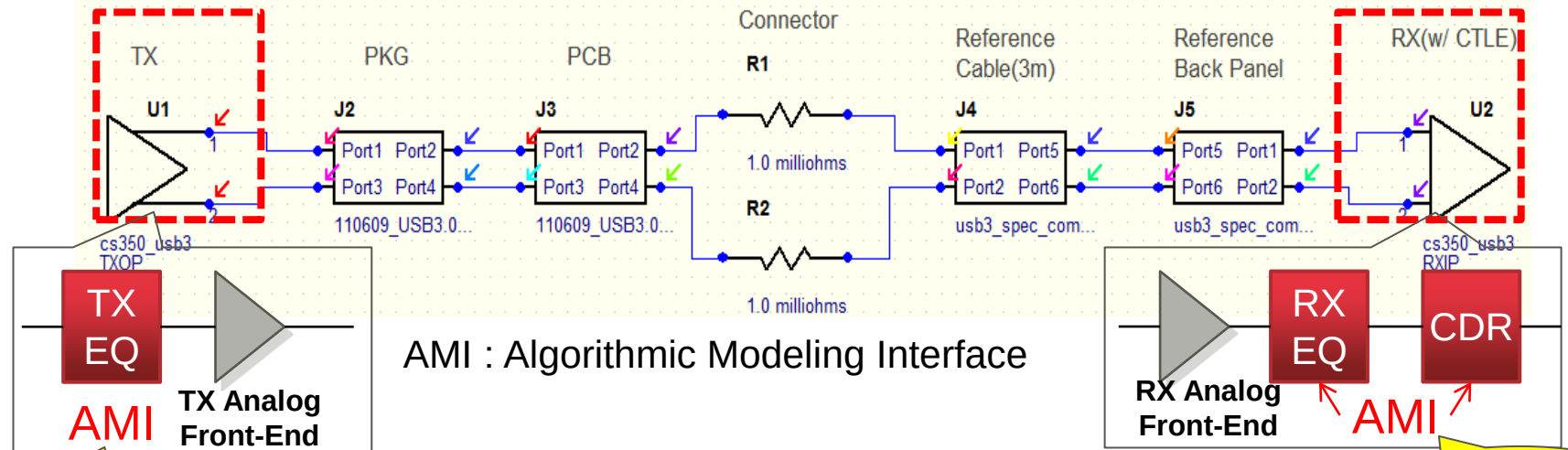
2. Convolution Process



We can execute the analysis of 1 million bits in 0.5 hours.

Characteristic of IBIS-AMI

■ IBIS-AMI



Binary data

[Algorithmic Model]

IBIS Example

Executable Windows_VisualC_32 TX_Wx32.dll TX.ami

Executable Windows_VisualC_64 TX_Wx64.dll TX.ami

Executable Linux_gcc4.4.2_32 TX_Lx32.so TX.ami

Executable Linux_gcc4.4.2_64 TX_Lx64.so TX.ami

[End Algorithmic Model]

Binary data

Windows/Linux
64bit/32bit

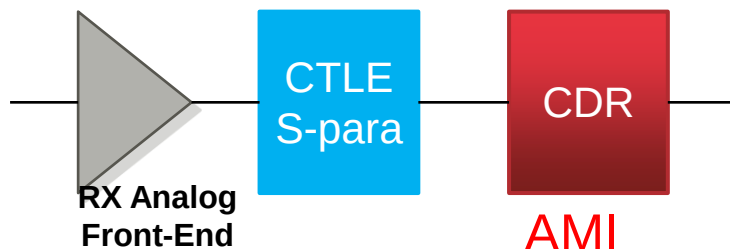
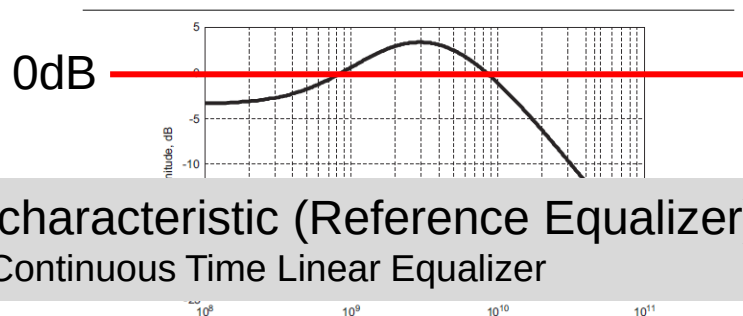
User can not correct IBIS-AMI,
because AMI parts are black box.



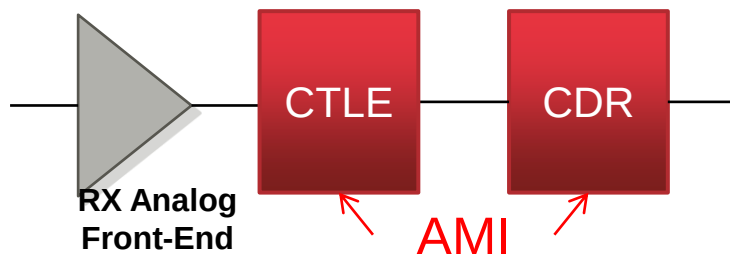
Model maker should verify the quality
of own IBIS-AMI. (each OS, EDA tool)

Trouble Case of IBIS-AMI Analysis (1/2)

Model dependence

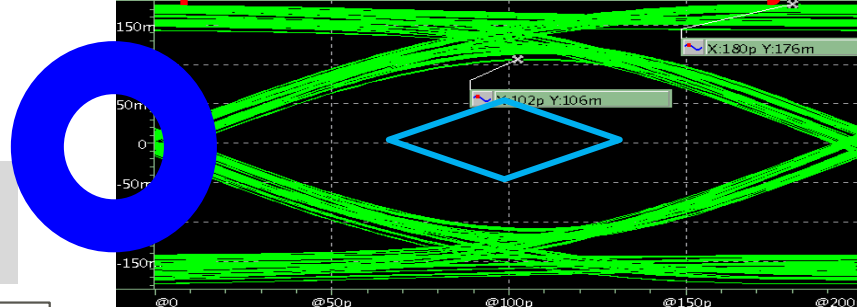


Some EDA tools are OK. Others are NG.

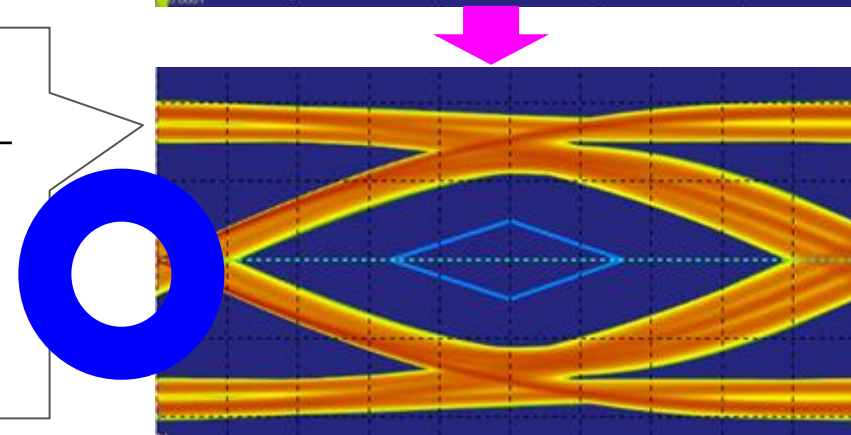
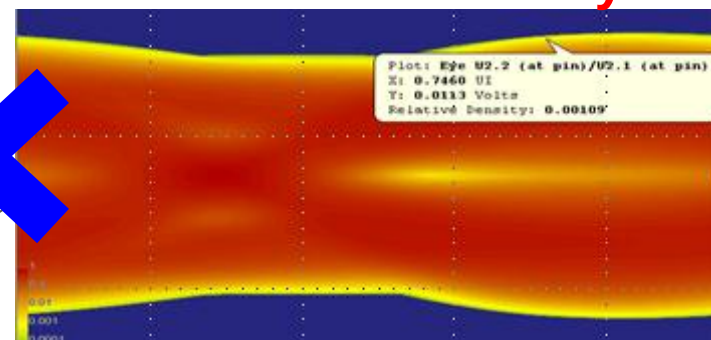


All EDA tools are OK.

Spice Net Transient Analysis



IBIS-AMI Channel Analysis



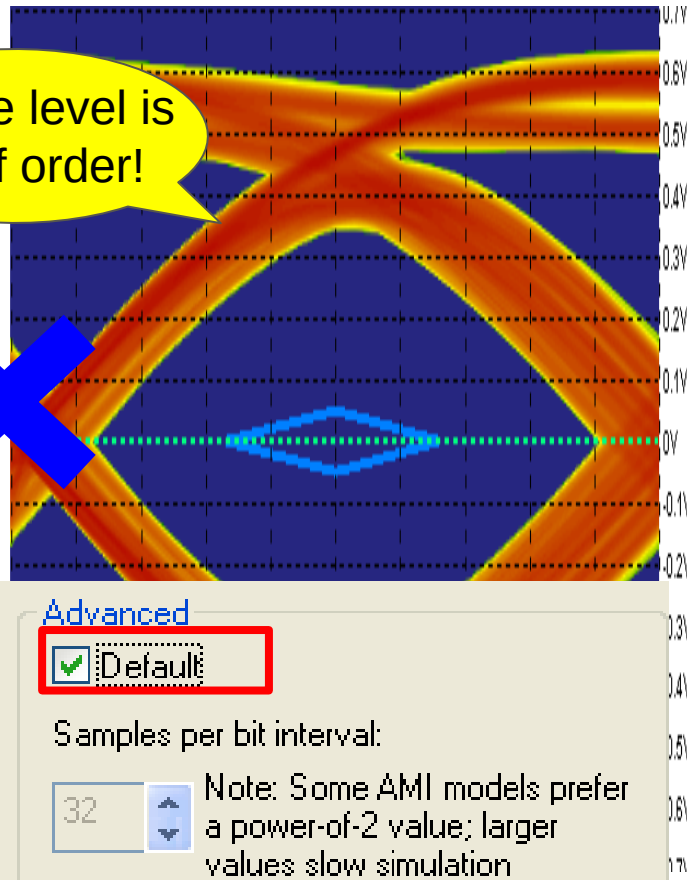
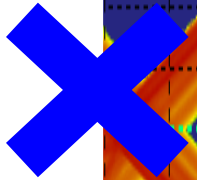
Trouble Case of IBIS-AMI Analysis (2/2)

■ Tool dependence

Samples Per Bit Interval

=> **Default Setting**

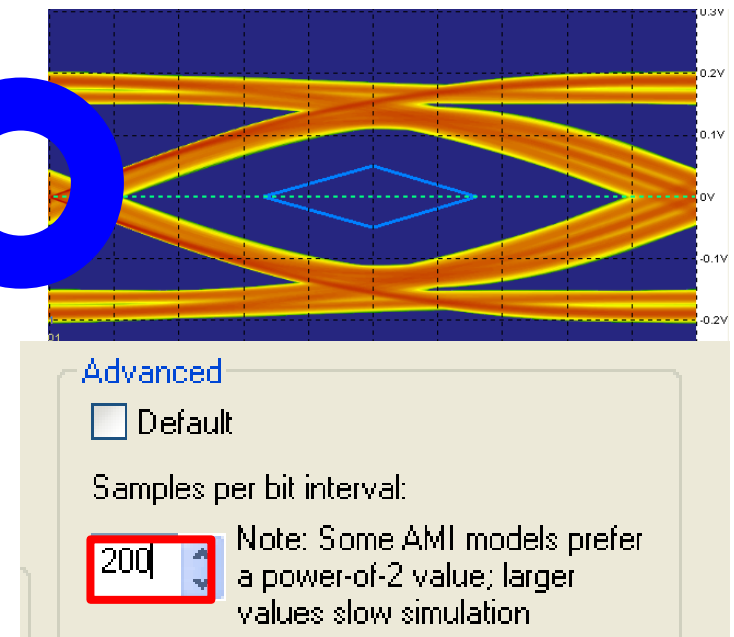
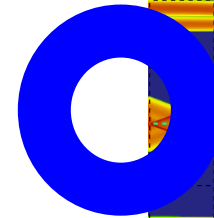
Voltage level is
out of order!



Samples Per Bit Interval

=> **Recommended setting**

The setting value depends
on modeling of IBIS-AMI.
It is necessary to use the
recommended value.

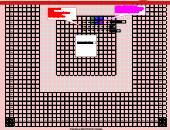


It is important that IBIS-AMI model maker solve various problems of “model and tool dependence”, before model maker release it.

Reference Design (Differential Analysis)

At the environment building

Ball Assign PCB Guide PCB Artwork



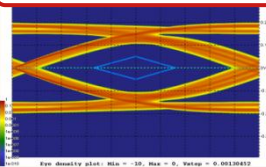
Tx/Rx Model

IBIS-AMI

Reference Cable+BP

S-Para

Sim Result

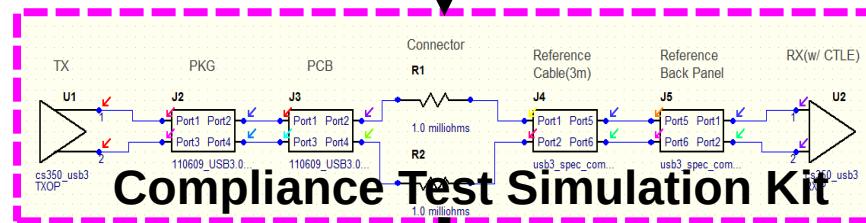


PKG Model

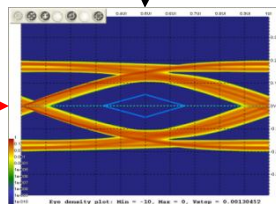
S-Para

PCB Model

S-Para



Compare

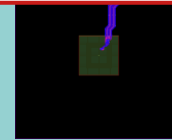
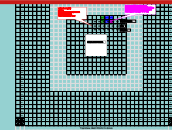


Compare

Differential Analysis

At the actual design

Ball Assign' PCB Artwork'



Customer Design

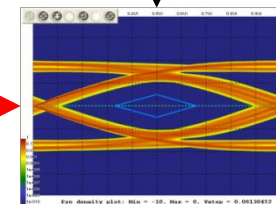
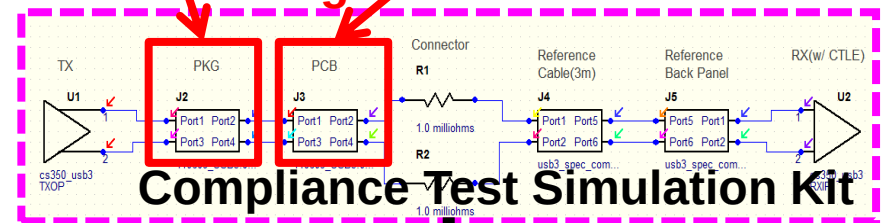
PKG Model'

S-Para

PCB Model'

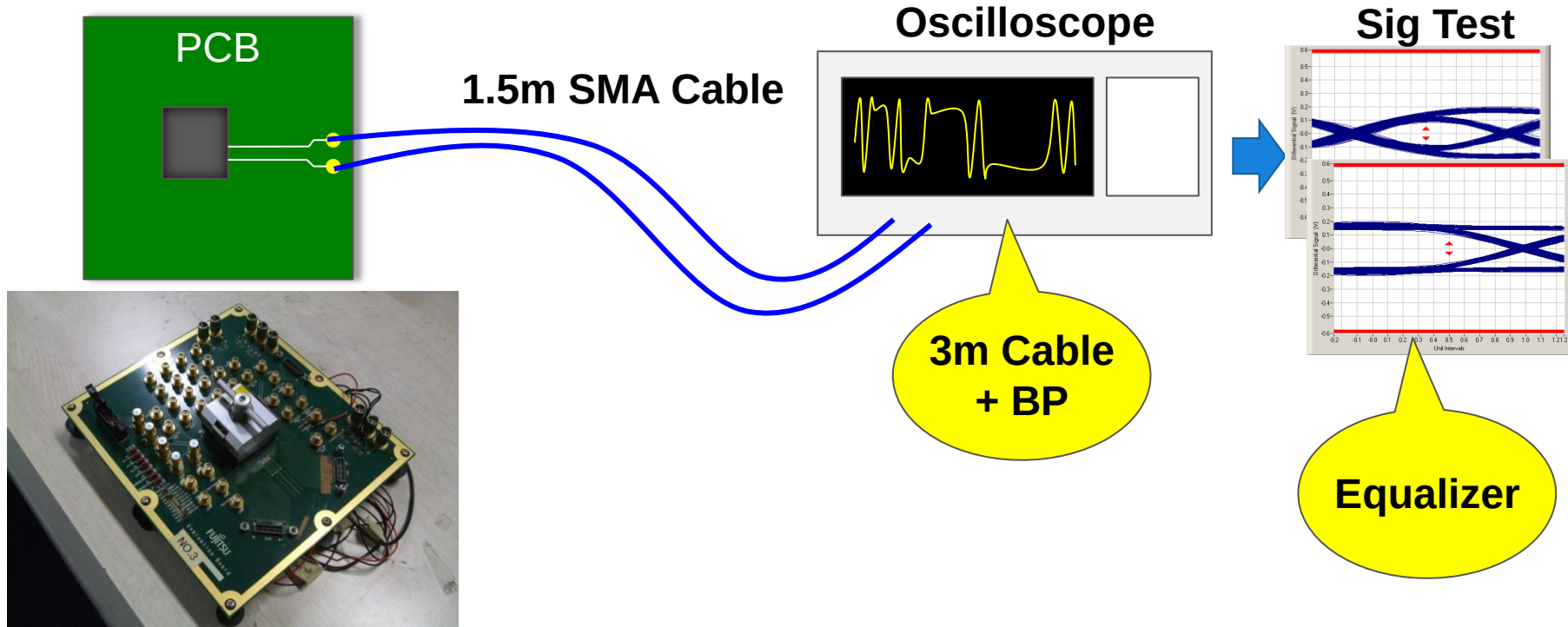
S-Para

Assign



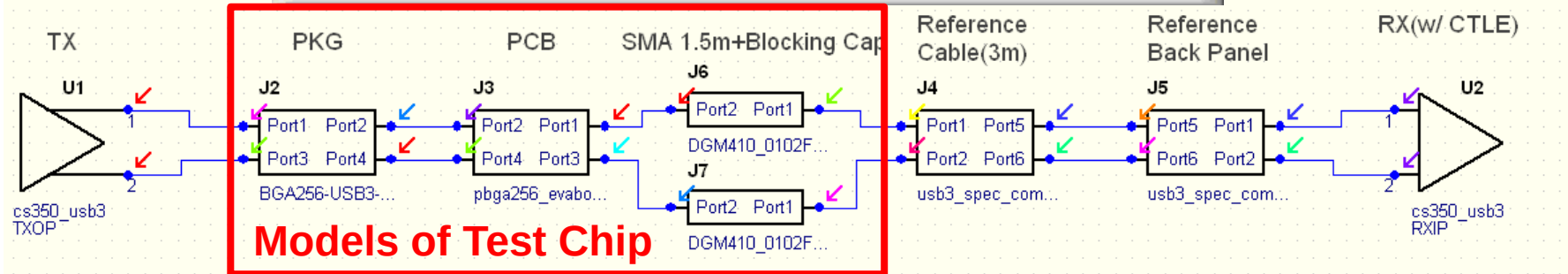
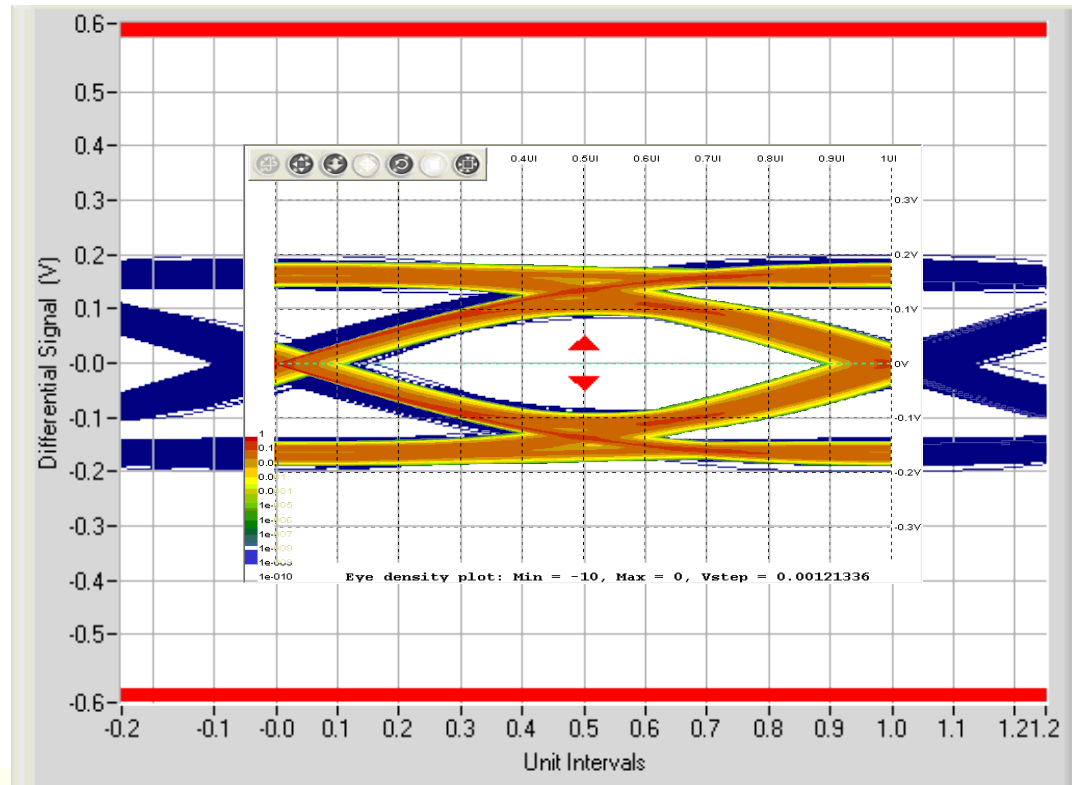
Measurement Correlation (1/2)

■ Measurement environment



Item	Comment
CHIP	USB3.0 Test Chip
PKG	Wire Bond BGA 4layer 256ball 27mm-square
PCB	6layer
PVT	Typical

■ Measurement vs Simulation

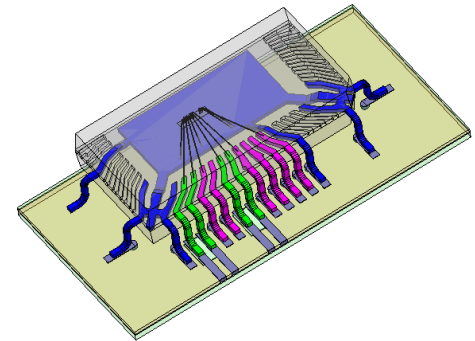
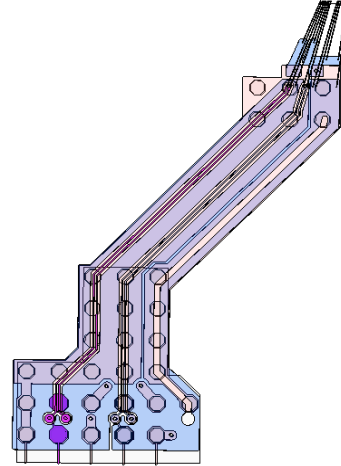
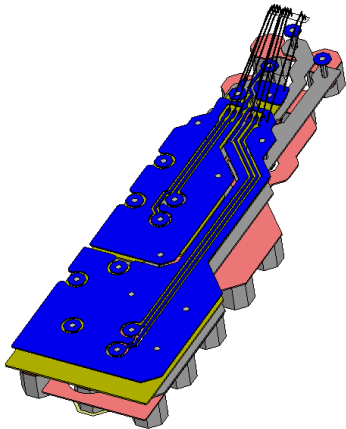
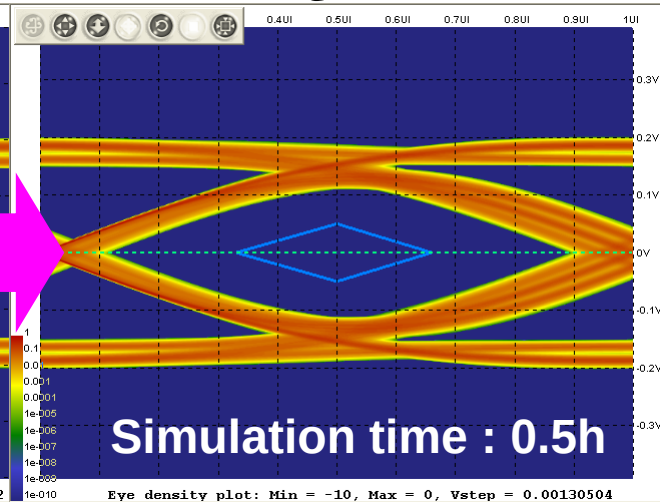
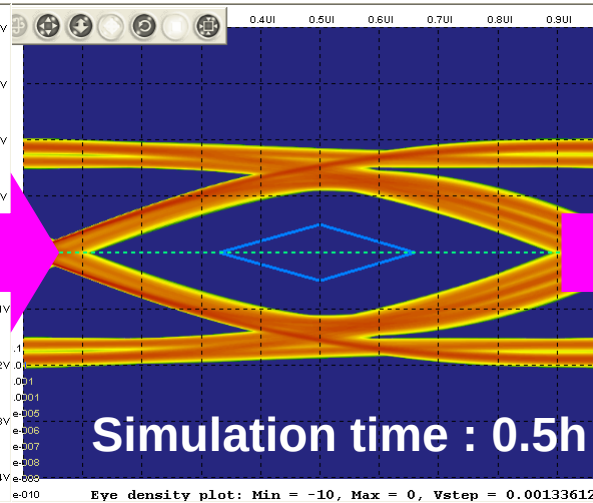
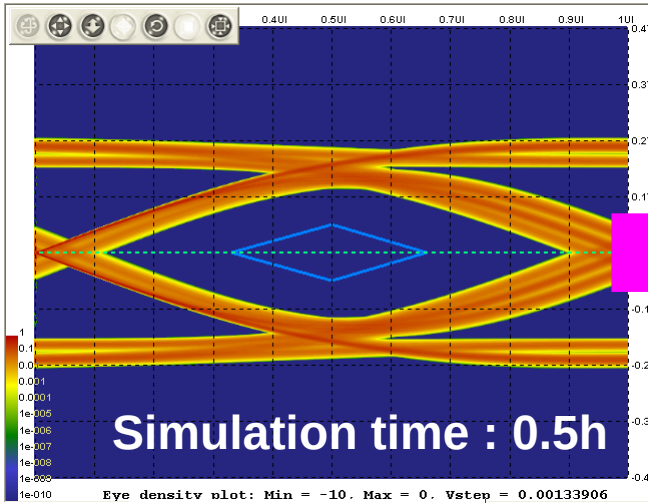


Application: Cost Reduction Study

PBGA 4layer

PBGA 2layer

LQFP



We can examine cost reduction of the product by using Simulation Kit in a short TAT.

- USB3.0 Compliance Simulation using IBIS-AMI Model
- Summary
- Expectation of IBIS-AMI

■ USB3.0 Compliance Simulation using IBIS-AMI Model

■ IBIS-AMI is a key technology of 5Gbps SerDes I/F analysis.

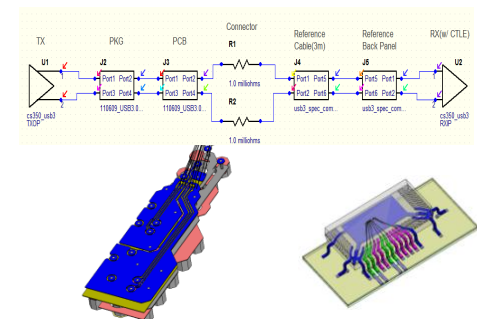
- High accuracy
- Short TAT

USB3.0

■ It is important that IBIS-AMI model maker solve various problems between IBIS-AMI and EDA tool beforehand.

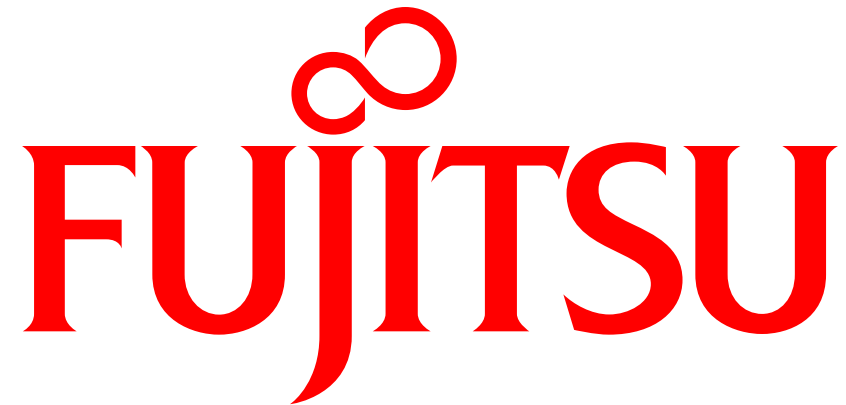


■ Simulation Kit constructed on EDA tool is able to contribute to short TAT analysis and cost reduction of the product.



- USB3.0 Compliance Simulation using IBIS-AMI Model
- Summary
- Expectation of IBIS-AMI

- We expect more information about IBIS-AMI.
 - Documents (IBIS-AMI Cookbook, Trouble shooting)
 - Samples (IBIS-AMI, Simulation result)
 - Visualization (EQ Characteristic)



shaping tomorrow with you